



Product Change Notification - RMES-05VMLN744 (Printer Friendly)

Date:

19 Feb 2018

Product Category:

Piezoelectric Horn Drivers; Photoelectric Smoke Detector

Notification subject:

CCB 2811 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected R&E Products available in 16L SOIC package at MMT assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected R&E Products available in 16L SOIC package at MMT assembly site.

Pre Change:

Gold (Au) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

| | Pre Change | Post Change |
|----------------------|-------------------------------------|-------------------------------------|
| Assembly Site | Microchip Technology Thailand (MMT) | Microchip Technology Thailand (MMT) |
| Wire material | Au | CuPdAu |

| | | |
|----------------------------------|--------|--------|
| Die attach material | 2200D | 2200D |
| Molding compound material | G600V | G600V |
| Lead frame material | CDA194 | CDA194 |

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 19, 2018 (date code: 1812)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

| Workweek | December 2016 | | | | | -- > | February 2018 | | | | March 2018 | | | | |
|-------------------------------|---------------|----|----|----|----|---------|---------------|----|----|----|------------|----|----|----|----|
| | 48 | 49 | 50 | 51 | 52 | | 05 | 06 | 07 | 08 | 09 | 10 | 11 | 12 | 13 |
| Initial PCN Issue Date | | | X | | | | | | | | | | | | |
| Qual Report Availability | | | | | | | | | X | | | | | | |
| Final PCN Issue Date | | | | | | | | | X | | | | | | |
| Estimated Implementation Date | | | | | | | | | | | | | X | | |

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

December 15, 2016: Issued initial notification.

February 19, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on March 19, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_RMES-05VMLN744_Affected_CPN.pdf](#)

[PCN_RMES-05VMLN744_Qual Plan.pdf](#)

[PCN_RMES-05VMLN744_Affected_CPN.xlsx](#)

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